

RECEIVED
CENTRAL FAX CENTER

JAN 30 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Group Art Unit: 1725

Applicant: Zafir Abdo, et al.

Examiner: Beveridge, Rachel E.

Serial No.: 10/692,403

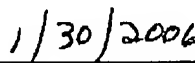
Atty. Docket: 2003P14606US

Filed: 10/23/2003

Title: TRANSIENT LIQUID PHASE BONDING TO COLD-WORKED
SURFACESMail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile transmission to the US Patent & Trademark Office fax number 571-273-8300 on the date shown below:

Response under 37 CFR 1.116 (3 pages)



David G. Maire, Reg. No. 34,865

Date

Beusse Wolter Sanks Mora & Maire, P.A.
390 North Orange Ave., Suite 2500
Orlando, FL 32801
telephone: 407-926-7704

10/692,403

JAN 30 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Group Art Unit: 1725

Applicant: Zafir Abdo, et al.

Examiner: Beveridge, Rachel E.

Serial No.: 10/692,403

Atty. Docket: 2003P14606US

Filed: 10/23/2003

Title: TRANSIENT LIQUID PHASE BONDING TO COLD-WORKED
SURFACESMail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450RESPONSE AFTER FINAL REJECTION UNDER 37 CFR 1.116

INTRODUCTORY COMMENTS

This paper is in response to the final rejection contained in the Office Communication mailed 12/13/2005. The applicants request that the Examiner reconsider the final rejection of this application in light of the following additional Remarks.

REMARKS

Claims 1-18 are pending in this application. Claims 1, 2, 5 and 10-18 are rejected under 35 USC 102 as being anticipated by Burke. Claims 3 and 7-9 are rejected under 35 USC 103 as being unpatentable over Burke. Claims 4 and 6 are rejected under 35 USC 103 as being unpatentable over Burke in view of Stenard.

The applicants request that the Examiner reconsider the teaching of Burke. Burke clearly emphasizes throughout his patent that the surfaces to be joined must be prepared in a very controlled manner in order to avoid recrystallization of the near-surface substrate material during the joining process. (See the Abstract; column 11,